

SmartSpice Analog Circuit Simulator



Device Models

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SmartSpice Background



- Development started in 1986 with 3A1; incorporated major changes and standardized software development on coding rules of 3C.1 and 3D.2 releases
- Objective - complete solution to Analog Circuit Simulation requirements
- True C/C++ language architecture to take advantage over the other vendors still based on FORTRAN language
- Final product has the advantage of being compatible with standard Berkeley SPICE syntax and data structures

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SmartSpice Background (cont.)



- Rapid acceptance as the industry standard worldwide
- Large customer base
- All major companies have a copy of SmartSpice
- Broad spectrum of users from individuals and Startups to large multinationals.

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Device Models



- Supports a comprehensive set of public domain device models
- All models support advanced convergence algorithms, temperature dependencies, gate capacitance models and geometry calculation methods

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Device Models (cont.)



- Comprehensive set of Intrinsic Device Models
 - **MOSFET**
 - BSIM1, BSIM3v3, BSIM4, BSIM5
 - Philips MOSS11, MOS20, EKV, HiSIM
 - User Models
 - **Bipolar**
 - Modified Gummel-Poon, Quasi-RC
 - Mextram, VBIC, HICUM, Modella
 - Macro Models to include parasitic device effects
 - User Models
 - **TFT**
 - Amorphous and RPI Polysilicon TFT
 - MESFET
 - Statz, Curtice I & II, TOM-2, TOM-3, TriQuint
 - **SOI**
 - Berkeley SOI, UFSOI
 - **Diode**
 - JunCap
 - **FRAM**
 - Ramtron model

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Device Models: BJTs



- LEVEL 1: Modified Gummel-Poon model
- LEVEL 2: Quasi RC (quasi-saturation) model

Bipolar Models



- MEXTRAM (Level=503):
 - Improved modeling of substrate effects and parasitic pnp
 - Improved approximation of distributed high frequency effects in the intrinsic base
- VBIC (Level=5):
 - Temperature dependency for knee currents and intrinsic/extrinsic resistances
 - BVBE model
 - High current roll-off
- HICUM (Level=6): High Current model for high speed applications
 - High collector currents (quasi-sat and saturation)
 - Large-signal transient applications
 - Good fit for SiGe HBTs

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MEXTRAM: Major Features



- LEVEL=504
- Modeling of SiGe devices
- Self-heating network
- Improved temperature scaling
- Reformulation of the epilayer model
- Simplified thermal noise model for the variable base resistance
- More flexibility in parameter extraction (additional parameters)
- Much smoother characteristics
- Better monotony in higher derivatives
- New phenomena like tunneling at Base-Emitter junction?

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VBIC: Major Features



- Improved Early effect modeling
- Parasitic PNP (substrate current effect)
- Quasi-saturation modeling with modified Kull model
- Constant overlap capacitances
- Weak avalanche model
- Improved depletion and diffusion capacitance
- First order modeling of distributed base
- Improved temperature modeling
- Excess phase network
- Self-heating
- HBT modeling ability

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VBIC: Major Features (cont.)



- Reach-through model to limit base-collector depletion capacitance
- Simple Base-Emitter breakdown model
- Fixed collector-substrate oxide capacitance
- Selector to switch to SGP qb formulation
- High current roll-off coefficient
- Separate IS allowed for reverse operation in HBTs
- Additional parameters added to extend temperature mappings
 - temperature dependence of IKF
 - separate coefficients for intrinsic and extrinsic resistances
 - separate activation energy for ISP

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VBIC: Additional Effects



- Weak avalanche model
 - Based on Kloosterman and De Graaff model (MEXTRAM)
- Base resistance split into intrinsic and extrinsic part
 - R_{bi} modulated by q_b to include depletion pinching and high injection effects
- Parasitic PNP device
 - Based on a partial GP model (no Early effect included)
 - Most important parts are I_{ccp} and Q_{bcp}
 - R_{bip} modulated by q_{bp} (similarly to R_{bi})
- Distributed base (first order approximation)
 - Partitioning of I_{be} and q_{je} across R_{bi}
 - Applies to both AC and DC modeling

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HICUM: Major Features



- Accurate description of the high-current operating region
- Distributed modeling of external base-collector region
- Emitter periphery injection and charge storage accounted for
- Bias dependent internal base resistance
- Prediction of temperature and process variations (scalability)
- Parasitic capacitances representing B-E and B-C oxide overlaps
- B-C weak avalanche breakdown and B-E tunneling
- Collector current spreading included in I_c and Q_f expressions
- Simple parasitic substrate transistor and RC network
- Self-heating and Non-Quasi-Static effects

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Device Models: BJTs



- LEVEL 500: Philips MODELLA model
 - Temperature effect
 - Charge storage effects
 - Excess phase shift for current and storage charges
 - Substrate effects
 - High-injection effects
 - Build-in electric field in base region
 - Bias-dependent early effect
 - low-level non-ideal base currents
 - Hard and quasi-saturation
 - Weak avalanche
 - Hot carrier effects in the collector epilayer
 - Explicit modeling of inactive region

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Hetrojunction Bipolar Transistor (HBT) Models



- LEVEL 20: UCSD-HBT model
 - Based on the standard SPICE Gummel-Poon model

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Device Models: MOSFETs



- LEVEL 1: Schichman-Hodges model
- LEVEL 2: Modified Schichman-Hodges model
- LEVEL 3: Semi-empirical model
- LEVEL 4: BSIM1
- LEVEL 7: BSIM3

Device Models: MOSFETs



- LEVEL 8: BSIM 3v3 (v3.2.5)
- Physical model based on process parameters
- Provides scalability and accuracy
- Single model provides good fit across all geometries and bias conditions with no binning requirements
- Suitable for both analog and digital applications
- Superb convergence achieved through continuous first and second derivatives

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BSIM3 Model



- Developed by UC Berkeley
- Most recent release is BSIM3 Version 3
- Physical and scalable properties
- Built-in W, L, Nch(x), TOX, XJ, RDS, LDD and T dependencies for drain current and first derivatives
- Support for current and future developments in MOSFET technologies
- Simulation of devices with channel length down to 0.13μ and oxide thickness down to 50A
- Can be used for statistical modeling

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BSIM3 Model (cont.)



- Threshold voltage reduction
- Mobility degradation due to gate vertical field
- Non-uniform doping effects
- Carrier velocity saturation and channel length modulation
- Drain induced barrier lowering (DIBL)
- Substrate current induced body effect
- Subthreshold current model
- Single I-V expression describes all operating regions
- Capacitance model for short and narrow geometry devices

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BSIM3 Model (cont.)



- Silvaco enhancements to the standard BSIM3 models include:
 - Advanced geometry and scaling models based on the Area Calculation Method
 - Temperature models consistent with other MOSFET models for both the model kernel and models parasitics
 - Multiplier for parallel connected devices
 - Devices outputs, such as terminal currents and device capacitances

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BSIM3 Version 3 Implementation



- BSIM3v3 Level 8 (SmartSpice) and Level 81 (Berkeley) produce virtually identical results
- Primary differences:
 - bug fixes
 - SmartSpice standard MOSFET model parameters: ACM, temperature, diode
 - additional parameters for the SmartSpice smooth functions: ABULKIM, NLIM, LAMBLIM, UEFFLIM, SMOOTH
 - additional BSIM3v3 output parameters
 - additional options VZERO and EXPERT

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BSIM3 Version 3 Convergence



- Berkeley smooth functions: V_{bseff} , V_{gsteff} , V_{dseff} , $V_{gs_overlap}$, V_{fb_eff}
- SmartSpice smooth functions for $A_{bulk} \geq 0.01$, $n \geq 1$, $\lambda = A_1 * V_{gsteff} + A_2 \leq 1$, N_{gate} , u_{eff}
- CONV option (GMIN and DCGMIN stepping algorithms)
- EXPERT option for discontinuity detection
- Convergence properties of BSIM3 Version 3 are better than convergence properties of BSIM3 Version 2

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Parameter Check in BSIM3 Model (cont.)



- In the original Berkeley BSIM 3.1 implementation, there are two types of checks - default (unconditional) check, and a check invoked by the parameter PARAMCHK=1:

Default Check

Fatal errors:

```

Leff <= 0.0
Weff <= 0.0
LeffCV <= 0.0
WeffCV <= 0.0
TOX <= 0.0
NLX < -Leff
NPEAK <= 0.0
NSUB <= 0.0
NGATE < 0.0
NGATE > 1.e25
XJ <= 0.0
DVT1 < 0.0
DVT1W < 0.0
W0 = -Weff
DSUB < 0.0
B1 = -Weff
CLC < 0.0
DELTA < 0.0
PCLM <= 0.0
DROUT < 0.0
Vsattemp <= 0.0
    
```

PARAMCHK=1 Check

Warnings:

```

Leff <= 5.0e-8
LeffCV <= 5.0e-8
Weff <= 1.0e-7
WeffCV <= 1.0e-7
TOX < 1.0e-9
NLX < 0.0
NPEAK <= 1.0e15
NPEAK >= 1.0e21
NSUB <= 1.0e14
NSUB >= 1.0e21
NGATE > 0.0 && <= 1.e18
DVT0 < 0.0
CDSC < 0.0
CDSCD < 0.0
ETA0 < 0.0
fabs(1e-6/(B1+Weff)) > 10
fabs(1e-6/(W0+Weff)) > 10
PDIBLC1 < 0.0
PDIBLC2 < 0.0

Vsattemp < 1.0e3
    
```

Corrected Errors:

```

if( CJSW>0.0 || CJSWG>0.0 ){
{
    if( PD < Weff)
        PD = Weff
    if( PS < Weff)
        PS = Weff
}
}
    
```

Corrected Errors:

```

if(A2 < 0.01)
    A2 = 0.01
if(A2 > 1.0)
    A2 = 1.0
A1 = 0.0
if(RDSW < 0.0)
    RDSW = 0.0
    Rds0 = 0.0
if(Rds0> 0.0 && Rds0 < 0.001)
    Rds0 = 0.0
if(CGDO < 0.0)
    CGDO = 0.0
if(CGSO < 0.0)
    CGSO = 0.0
if(CGBO < 0.0)
    CGBO = 0.0
    
```

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BSIM4 MOSFET Model



- Level=14 : original SmartSpice implementation
- Level=54 : compatibility with HSPICE(TM) implementation
- Improvements and additions over BSIM3v3
- Accurate new model of the intrinsic input resistance
- Flexible substrate resistance network
- New accurate channel thermal noise and flicker noise
- NQS model consistent with Rg-based RF model
 - Accurate gate direct tunnelling model
 - Comprehensive geometry-dependent parasitics model
 - Asymmetrical and bias-dependent S/D model
 - More accurate mobility model
 - GIDL current model
 - Quantum mechanical charge-layer-thickness model
 - Different diode IV and CV characteristics

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Device Models: MOSFETs



- LEVEL 14 : BSIM4
 - Accurate model of the intrinsic input resistance for both RF, high-frequency analog and high-speed digital applications
 - Flexible substrate resistance network for RF modeling
 - New accurate channel thermal noise model and noise partition model for the induced gate noise
 - Non-quasi-static (NQS) model, consistent with the R_g -based RF model and consistent AC model, accounting for the NQS effect in both transconductances and capacitances
 - Accurate gate direct tunneling model
 - Comprehensive geometry-dependent parasitics model for various source/drain connections and multi-finger devices
 - Improved model for steep vertical retrograde doping profiles
 - Better model for pocket-implanted devices in V_{th} , bulk charge effect, and R_{out} equations

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Device Models: MOSFETs (cont.)



- LEVEL 14 : BSIM4 (continued)

- Asymmetrical and bias-dependent source/drain resistance, either internal or external to the intrinsic MOSFET
- Acceptance of either the electrical or physical gate
- Oxide thickness as the model input at the user's choice in a physically accurate manner
- Quantum mechanical charge-layer-thickness model for both IV and CV
- More accurate mobility model for predictive modeling
- Gate-induced drain leakage (GIDL) current model, available in BSIM for the first time
- Improved unified flicker ($1/f$) noise model, smooth over all bias regions and accounting for the bulk charge effect
- Different diode IV and CV characteristics for source and drain junctions
- Junction diode breakdown with or without current limiting
- Gate dielectric constant defined as a model parameter

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Device Models: MOSFETs (cont.)



- LEVEL 55 : BSIM5
 - Built on the well-proven BSIM4
 - Improvements with regard to previous BSIM3v3 and BSIM4 :
 - Fully physical and symmetric
 - Improved reciprocity (no negative capacitances)
 - Better model for moderate inversion region
- ↪ Better core using as much as possible of BSIM4 features

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Device Models: MOSFETs (cont.)



- LEVEL 11: Philips MOS11 model
 - Dedicated to analog, RF and digital simulation
 - Physics based
 - Based on surface potentials
 - Accurate transition from weak to strong inversion
 - Single equation for the whole operating range
 - Symmetrical
 - Good distortion behavior (accurate description of high-order derivatives)

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Device Models: MOSFETs (cont.)



- LEVEL 20: Philips MOS20 model
 - High-Voltage MOSFET model
 - Especially developed to describe LDMOS, EPMOS and VDMOS models
 - Acts as a replacement for the couple MOS9+MOS30
 - Includes the following effects:
 - Surface potentials computation avoiding smoothing functions between operating regimes
 - Mobility reduction
 - Velocity saturation
 - Drain-Induced Barrier Lowering (DIBL)
 - Static feedback
 - Channel length modulation
 - Weak avalanche current

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Device Models: MOSFETs (cont.)



- LEVEL 44: EKV MOSFET model
 - Simulation of low voltage, low current analog and mixed signal circuits using submicron CMOS technologies
 - EKV model equation is based on single expression, preserves continuity of first and higher order derivatives
 - Includes the following physical effects:
 - Effects of doping profile, substrate effect
 - Modeling of weak, moderate and strong inversion behavior
 - Modeling of mobility effect due to vertical field
 - Short channel effects for velocity saturation, channel length modulation (CLM), source and drain charge-sharing (including for narrow channel widths), reverse short-channel effect (RSCE)
 - Modeling of substrate current due to impact ionization
 - Quasi-static charge-based dynamic model
 - Thermal and flicker noise modeling

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Device Models: MOSFETs (cont.)



- LEVEL 88: High voltage MOSFET model
 - Forward and reverse mode of operations
 - Asymmetry of all parasitics (diodes and resistances)
 - Bias dependence of external resistances RDS
 - Dependence mobility degradation on V_{ds}
 - Bias dependent V_{SAT}
 - Transconductance G_m reduction in saturation at high V_{ds}

HiSIM MOSFET Model



- HiSIM version 1.2.0
- Computes surface potentials, from the drift-diffusion approximation
 - No parameter inter-dependence
 - Easy parameter extraction
 - Low number of parameters
 - Continuity of derivatives
 - One parameter set for all channel lengths

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Device Models: MOSFETs



- LEVEL 111: HiSIM MOSFET model
- Computes surface potentials, from the drift-diffusion approximation
 - No parameter inter-dependence
 - Easy parameter extraction
 - Low number of parameters
 - Continuity of derivatives
 - One parameter set for all channel lengths

Thin Film Transistors (TFT) Models



- Amorphous-Silicon TFT models:
 - LEVEL 15: Modified Leroux model
 - Transport by multitraps
 - Channel length modulation (CLM)
 - Exponential localized states density
 - Temperature dependence
 - Overlap resistance R_c

TFT Models - Leroux's Model a-Si (Level 15)



- Leakage current : empirical equation
- Exponential dependence of subthreshold current with v_{gs}
- CLM effect taken into account in saturation region
- Temperature dependence
- Charge-conservation model (fast convergence in transient)
- Transitions with model parameters : V_{GHIGH} , V_{GLOW}
- Simple but well proven model

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TFT Models - RPI Models a-Si and poly-Si



- Semi-empirical and unified model to achieve very good convergence
 - Interpolation techniques and smoothing functions (V_{dse} , V_{gte})
 - no transition model parameters
- AC model accurately reproduces capacitance frequency dispersion
- Automatic scaling of model parameters to accurately model a wide range of device geometries
- Numerous industrial collaborations : Xerox, Philips, IBM,
- Recent model

$$I_{drain,unified} = \left(\frac{I_a I_{sub}}{I_a + I_{sub}} \right) + I_{leak}$$

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RPI Polysilicon and Amorphous TFT Models



- Self heating is added to both models via single internal thermal mode. Thermal circuit is represented with a thermal resistance and capacitance in parallel
- New charge conservation model based on Leroux's model founded on a single parameter

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Thin Film Transistors (TFT) Models



- LEVEL 35: Modified RPI model
 - Unified DC model covers all regimes of operation
 - AC model accurately reproduces frequency dispersion of capacitances
 - Provides automatic scaling of model parameters to accurately model a wide range of device geometries

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Thin Film Transistors (TFT) Models (cont.)



- Polysilicon TFT models:
 - LEVEL 16: Modified U.C. Berkeley SPICE 3E1 model
 - Hot carrier
 - Drain induced barrier lowering (DIBL)
 - Channel length modulation (CLM)
 - Thermal generation
 - Gate induced drain leakage (GIDL)

Thin Film Transistors (TFT) Models (cont.)



- LEVEL 36: Modified RPI model
 - Guarantees stability and conversion
 - Unified DC model covers all regimes of operation
 - AC model accurately reproduces frequency dispersion of capacitances
 - Provides automatic scaling of model parameters to accurately model a wide range of device geometries

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SOI Model Features



- Continuity of DC current and its derivatives in all regions of operation
- Charge and physical based model
- Charge-conservation models
- Suitable for deep-submicron devices
- Scalable and accurate model
- DC, AC, transient and noise analysis
- Floating body voltage iterated by SPICE engine (determined by body currents)

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Advanced SPICE Model Implementation in SmartSpice: SOI Model Objectives



- Dynamic depletion is applied on both I-V and C-V. Charge and Drain current are scaleable with T_{box} and T_{si} continuously
- Supports external body bias and backgate bias; a total of 6 nodes
- Real floating body simulation in both I-V and C-V. Body potential is properly bounded by diode and C-V formulation
- Self heating implementation improved over the alpha version

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Advanced SPICE Model Implementation in SmartSpice: SOI Model Objectives (cont.)



- An improved impact ionization current model
- Various diode leakage components and parasitic bipolar current included
- New depletion charge model (EBCI) introduced for better accuracy in capacitive coupling prediction. An improved BSIM3v3 based model is added as well
- Dynamic depletion selector (ddMod) to suit different requirements for SOI technologies
- Single I-V expression as in BSIM3v3.1 to guarantee continuities of I_{ds} , G_{ds} and G_m and their derivatives for all bias conditions

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SOI Models



- LEVEL 21 : UFS (Florida) SOI model fully depleted:
 - Physically accounts for the charge coupling between the front and the back gates
 - 2-D analysis for the subthreshold region of operation has been added
 - Accumulation of charge in the body has been also added, it can drive dynamic floating-body bipolar effects
 - Accounts for DC and dynamic floating-body effects in all regions of operation

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Berkeley SOI Models: Main Features



- Derived from BSIM3v3 equations (well experienced model)
- Single I-V expression
- Smoothing and clipping functions to unify all regions of operation (v_{gsteff} , v_{bseff} , v_{dseff} , ...)
- Semi-empirical
- Lot of model parameters
- Checking of model parameters
- Dynamic depletion mode
- Design simulated : ring oscillator, sram (~ 1000 transistors)

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SOI Models



- LEVEL 25: BSIM3 SOIv1 model derived from BSIM3v3.1
 - Partially Depleted (PD) and fully depleted (FD) devices
 - Dynamic and continuous transitions between PD and FD
- LEVEL 26: BSIM3 SOIv2 fully depleted (FD) model
 - Has improved simulation efficiency and noise modeling
 - Supports external body bias and backgate bias (5 ext nodes)
 - Improved self-heating implementation
 - Single I-V expression as in BSIM3v3 guarantees continuities of I_{ds} , G_m , and G_{ds} and their derivatives for all bias conditions

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SOI Models (cont.)



- LEVEL 27: BSIM3 SOlv2 dynamic depletion (DD) model
 - The dynamic depletion approach is applied on both I-V and C-V
 - Charge and drain current are scalable
 - same features as in LEVEL = 26
- LEVEL 29: BSIM3 SOlv2 partially depleted (PD) model
 - Real floating body simulation in both C-V and I-V. The body potential is determined by the balance of all the body current components
 - Enhancements in the threshold voltage and bulk charge formulation of the high positive body bias regime
 - An improved parasitic bipolar current model
 - An improved impact ionization current model

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SOI Models (cont.)



- LEVEL 33 : BSIM3 SOIv3
 - Includes Partially and Fully depleted models
 - PD module identical to BSIM3 SOIv2
 - Improved FD module
 - Ideal Fully Depleted model for strongly FD devices (without floating body effect)
 - Non Ideal Fully Depleted model
 - Automatic selection among the above modes
 - New Gate-to-channel and Gate-to-Source/Drain currents
 - New gate resistances model, including RF

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SOI Models (cont.)



- LEVEL 32: CEA/LETI model (LETISOI)
 - For modeling the static and dynamic electrical behavior of partially-depleted SOI devices
 - Only uses pure analytical current and charge equations

FRAM Model



- Based on original RAMTRON model
- Three parallel elements: a linear capacitor, a resistor and a current source
- Improved scalability with area
- Improved convergence and accuracy through continuous derivatives
- Parameter clipping for convergence
- Proportion of domains switched

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Device Models: Diodes



- LEVEL 1: Standard junction diode model
(non geometric model)
- LEVEL 2: Fowler-Nordheim diode model
 - Created as metal-semiconductor or s-m-s
 - The insulator of this type of diode is very thin (about 100 \AA), which allows for the tunneling of the carriers
 - Modeling electrically-alterable memory cells and other insulation breakdown devices
 - In many applications, they are in parallel together. The multiplier M is then used to simplify the simulation

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Device Models: Diodes (cont.)



- LEVEL 3: Junction diode model (geometric model)
- LEVEL 9: Philips JUNCAP diode model
- LEVEL 500: Philips LEVEL 500 diode model
 - Forward biasing (ideal current, non ideal current including tunneling)
 - Reverse biasing (Trap assisted tunneling, Shockley-Read-Hall generation, band-to-band tunneling, avalanche multiplication)
 - Breakdown
 - Series resistances
 - Charge storage effects
 - temperature scaling rules
 - Noise model for RS and the ideal forward current

Device Models: Diodes (cont.)



- LEVEL 4: RPI VCSEL laser diode
 - Vertical Cavity Surface Emitting Laser
 - Mixed Electronic/Photonic (MEP) simulation : photonic part described in terms of equivalent electrical signal
 - Can be connected to transmission line and optical receiver devices

Device Models: JFETs



- LEVEL 1: Basic SPICE model with Sydney University enhancements
- LEVEL 2: Modified SPICE model with gate modulation of LAMBDA
 - Takes into consideration the dependence of channel length modulation on gate voltage (by means of the model parameter LAM1)

Device Models: MESFETs



- LEVEL 1: JFET model
- LEVEL 2: Statz model
- LEVEL 3: Curtice model
- LEVEL 4: Curtice-Ettenburg model
- LEVEL 5: TriQuint model
- LEVEL 6: Parker Skellern model
- LEVEL 7: TriQuint-2 model

Passive Elements and Independent Sources



- Resistors
- Capacitors
- Inductors
- Mutual inductors and magnetic cores
- Switches
- Independent voltage, current, DC, AC, transient or mixed sources

Transmission Lines



- Lossless Transmission Line
- Berkeley Lossy Transmission Line Model
- Lossy Transmission Line - Recursive Convolution Model
- W Element - Multiconductor Lossy frequency Dependent Transmission Line (Under development)

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Analog Behavioral Modeling



- Analog Behavioral Device
 - Unique SmartSpice device
 - The current through/voltage across can be an arbitrary mathematical expression referencing node voltage and device current
 - The expression can contain the derivative operator
 - Expressions can contain if...then...else conditions
 - Expressions can access the circuit temperature, current, time and current timestep(tstep)
 - Delay-type device can be used to model an ideal delay

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Controlled Sources



- Voltage Controlled Voltage Source
- Current Controlled Current Source
- Voltage Controlled Current Source
- Current Controlled Current Source

Conclusion



- The complete set of industry standard models are available
- Berkley compatible syntax form for quick model implementation
- Long history of experience with large customer base and diverse customer applications

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